

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (cancelled)
2. (cancelled)
3. (cancelled)
4. (cancelled)
5. (cancelled)
6. (cancelled)
7. (cancelled)
8. (cancelled)
9. (cancelled)
10. (cancelled)
11. (cancelled)
12. (cancelled)
13. (cancelled)
14. (cancelled)
15. (cancelled)
16. (cancelled)
17. (cancelled)
18. (cancelled)
19. (cancelled)
20. (previously presented): A wafer handling system comprising a six axis robot having an operative end; a dry wafer gripping device attached to said robot operative end; and a wet wafer gripping device attached to said robot operative end.

21. (cancelled)
22. (cancelled)
23. (cancelled)
24. (cancelled)
25. (currently amended): A method for transferring workpieces comprising the steps of:
 retrieving said workpieces from a first station with a robot;
 flipping said workpieces over with said robot;
 placing said workpieces on a second station with said robot;
 retrieving said workpieces from a third station with said robot after said workpieces are moved from the second station to the third station with a flipper arm that is separate from, and not a part of, the robot; and
 placing said workpieces on said first station with said robot, wherein said robot includes at least one workpiece gripping device for retrieving and holding said workpieces which includes a dry end-effector for gripping dry workpieces and a wet end-effector for gripping wet workpieces.
26. (previously presented): A method as claimed in claim 25, wherein said workpieces are retrieved from a tilted cassette in said first station and transferred with said dry end-effector to an index table in said second station.
27. (previously presented): A method as claimed in claim 26, wherein said third station comprises a rinsing station and a drying station, and comprising the additional step of transferring said workpieces from said rinsing station to said drying station with said wet end-effector.
28. (previously presented): A method as claimed in claim 27, wherein said workpieces are retrieved from said drying station with said dry end-effector and transferred to said cassette.
29. (previously presented): A method as claimed in claim 28, wherein said robot has six axes to permit movement of said end-effectors among said tilted cassette, said index table, said rinsing station, and said drying station.

30. (previously presented): A wafer handling system as claimed in claim 20, wherein said dry wafer gripping device is a dry end-effector and said wet wafer gripping device is a wet end-effector.

31. (previously presented): A wafer handling system as claimed in claim 30, wherein said dry end-effector and said wet end-effector are oriented substantially orthogonal to each other.

32. (new): A method for robotically transferring semiconductor wafers between a plurality of stations of a machine for performing multiple operations on the wafers using a robot equipped with a dry end-effector and a wet end-effector for handling wafers, the method comprising:

transporting dry wafers from a cassette to an index station with the dry end-effector;

transporting wet wafers from a rinse station to a spin-dry station with the wet end-effector; and

transporting dry wafers from the spin-dry station to another cassette with the dry end-effector.

33. (new): The method of claim 32, wherein transporting dry wafers from a cassette to an index station comprises flipping the wafers.